

**ENHANCED PERFORMANCE SURFACE MOUNT SEMICONDUCTOR
PACKAGE DEVICES AND METHODS**

ABSTRACT

[0026] A surface mount semiconductor device package and method is disclosed. The surface mount semiconductor device package is compact and minimizes the length of bond wires in order to minimize series inductance. The encapsulant material is of low dielectric constant in order to minimize parasitic capacitance. The substrate material is selected to improve heat transfer characteristics. The features of the invention offer increased high frequency performance.

E:\Clients\Microsemi - 1820\2007\patent.wpd

09/27/2007 16:02:04